

N-channel TrenchMOS logic level FET Rev. 03 — 22 February 2008

Product data sheet

#### **Product profile** 1.

#### 1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using Nexperia High-Performance Automotive (HPA) TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

#### 1.2 Features

- 175 °C rated
- Q101 compliant

#### 1.3 Applications

- 12 V and 24 V loads
- General purpose power switching
- Logic level compatible
- Very low on-state resistance
- Automotive systems
- Motors, lamps and solenoids

#### 1.4 Quick reference data

#### Table 1. **Quick reference**

Parameter	Conditions	Min	Тур	Max	Unit
drain current	$V_{GS} = 5 \text{ V}; T_{mb} = 25 \text{ °C};$ see <u>Figure 1</u> and <u>4</u>	-	-	26	A
total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>	-	-	59	W
aracteristics					
drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 15 \text{ A};$ $T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 12}{13} \text{ and } \frac{13}{13}$	-	34	40	mΩ
he ruggedness					
non-repetitive drain-source avalanche energy	$ \begin{split} I_D &= 26 \text{ A}; \ V_{sup} \leq 55 \text{ V}; \\ R_{GS} &= 50 \ \Omega; \ V_{GS} = 5 \text{ V}; \\ T_{j(init)} &= 25 \ ^\circ\text{C}; \ unclamped \end{split} $	-	-	36	mJ
	drain current total power dissipation aracteristics drain-source on-state resistance he ruggedness non-repetitive drain-source avalanche	$\label{eq:GS} \begin{array}{ll} \text{drain current} & \text{V}_{\text{GS}} = 5 \text{ V};  \text{T}_{\text{mb}} = 25 ^{\circ}\text{C};\\ \text{see } \underline{\text{Figure 1}} \text{ and } \underline{4} \\ \text{total power dissipation} & \text{T}_{\text{mb}} = 25 ^{\circ}\text{C}; \text{ see } \underline{\text{Figure 2}} \\ \textbf{aracteristics} \\ \text{drain-source on-state} & \text{V}_{\text{GS}} = 5 \text{ V};  \text{I}_{\text{D}} = 15 \text{ A};\\ \text{T}_{\text{j}} = 25 ^{\circ}\text{C}; \text{ see } \underline{\text{Figure 12}} \text{ and } \\ \underline{13} \\ \textbf{he ruggedness} \\ \text{non-repetitive} & \text{I}_{\text{D}} = 26 \text{ A};  \text{V}_{\text{sup}} \leq 55 \text{ V};\\ \text{R}_{\text{GS}} = 50  \Omega;  \text{V}_{\text{GS}} = 5 \text{ V}; \end{array}$	$\begin{array}{llllllllllllllllllllllllllllllllllll$	$\begin{array}{c} \text{drain current} & \text{V}_{\text{GS}} = 5 \text{ V};  \text{T}_{\text{mb}} = 25 ^{\circ}\text{C}; & \text{-} & \text{-} \\ \text{see Figure 1} \text{ and } \underline{4} & \text{-} & \text{-} \\ \text{total power dissipation} & \text{T}_{\text{mb}} = 25 ^{\circ}\text{C}; \text{ see Figure 2} & \text{-} & \text{-} \\ \text{naracteristics} & & & \\ \text{drain-source on-state} & \text{V}_{\text{GS}} = 5 \text{ V}; \text{ I}_{\text{D}} = 15 \text{ A}; & \text{-} & 34 \\ \text{resistance} & & \text{T}_{j} = 25 ^{\circ}\text{C}; \text{ see Figure 12} \text{ and} \\ \underline{13} & & \\ \text{he ruggedness} & & \\ \text{non-repetitive} & \text{I}_{\text{D}} = 26 \text{ A};  \text{V}_{\text{sup}} \leq 55 \text{ V}; & \text{-} & \text{-} \\ \text{drain-source avalanche} & \text{R}_{\text{GS}} = 50  \Omega;  \text{V}_{\text{GS}} = 5 \text{ V}; \end{array}$	drain current $V_{GS} = 5 \text{ V}; T_{mb} = 25 \text{ °C};$ see Figure 1 and 4-26total power dissipation $T_{mb} = 25 \text{ °C};$ see Figure 2 aracteristics59drain-source on-state resistance $V_{GS} = 5 \text{ V}; I_D = 15 \text{ A};$ $T_j = 25 \text{ °C};$ see Figure 12 and $13$ -3440he ruggednessID= 26 \text{ A}; V_{sup} \le 55 \text{ V}; $R_{GS} = 50 \Omega; V_{GS} = 5 \text{ V};$ 36

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### 2. Pinning information

Table 2.	Pinning			
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	mb	D
2	S	source		$\dot{\frown}$
3	S	source		G_(IET)
4	G	gate	Ч	
mb	D	mounting base; connected to drain	Ŭ Ŭ Ŭ Ŭ 1 2 3 4 SOT669 (LFPAK)	mbb076 S

# 3. Ordering information

#### Table 3.Ordering information

Type number	Package	Package				
	Name	Description	Version			
BUK9Y40-55B	LFPAK	plastic single-ended surface-mounted package (LFPAK); 4 leads	SOT669			

### 4. Limiting values

#### Table 4.Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	$T_j \ge 25 \text{ °C}; T_j \le 175 \text{ °C}$	-	55	V
V <sub>DGR</sub>	drain-gate voltage	$R_{GS}$ = 20 k $\Omega$	-	55	V
V <sub>GS</sub>	gate-source voltage		-15	15	V
I <sub>D</sub>	drain current	$T_{mb}$ = 100 °C; $V_{GS}$ = 5 V; see <u>Figure 1</u>	-	18	А
		$T_{mb}$ = 25 °C; $V_{GS}$ = 5 V; see <u>Figure 1</u> and <u>4</u>	-	26	А
I <sub>DM</sub>	peak drain current	$T_{mb}$ = 25 °C; $t_p \leq$ 10 $\mu s;$ pulsed; see Figure 4	-	106	А
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; see <u>Figure 2</u>	-	59	W
T <sub>stg</sub>	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
Avalancl	he ruggedness				
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	$\label{eq:ld} \begin{array}{l} I_D = 26 \text{ A};  V_{sup} \leq 55 \text{ V};  \text{R}_{GS} = 50  \Omega;  \text{V}_{GS} = 5 \text{ V}; \\ T_{j(\text{init})} = 25 \ ^{\circ}\text{C}; \text{ unclamped} \end{array}$	-	36	mJ
E <sub>DS(AL)R</sub>	repetitive drain-source avalanche energy	see Figure 3	[1][2] [3]	-	J
Source-o	drain diode				
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C	-	26	А
I <sub>SM</sub>	peak source current	$t_p \le 10 \ \mu s$ ; pulsed; $T_{mb}$ = 25 °C	-	106	А

[1] Single-pulse avalanche rating limited by maximum junction temperature of 175  $^\circ$ C.

[2] Repetitive avalanche rating limited by average junction temperature of 170 °C.

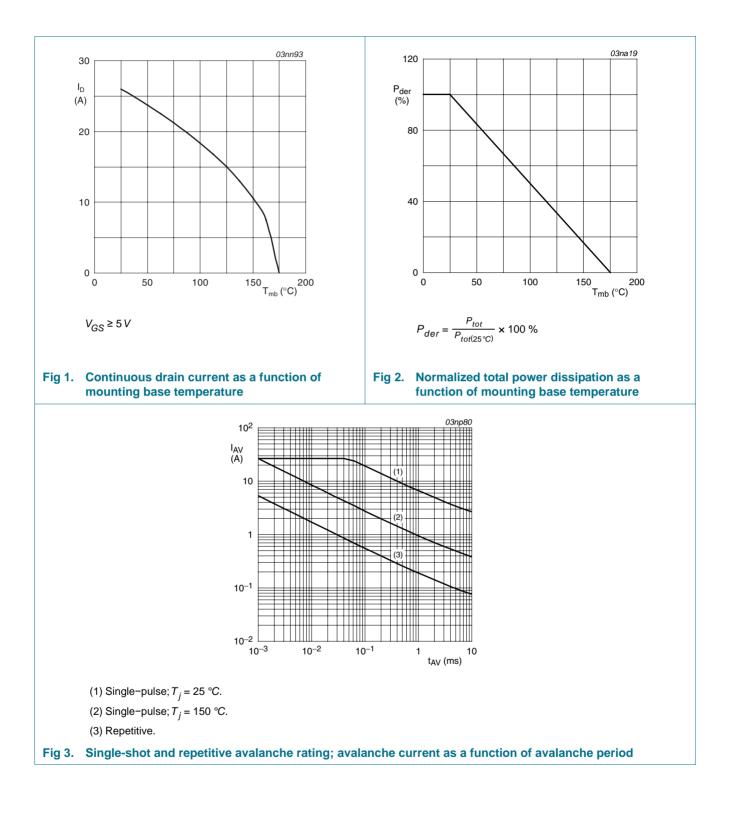
[3] Refer to application note AN10273 for further information.

BUK9Y40-55B\_3

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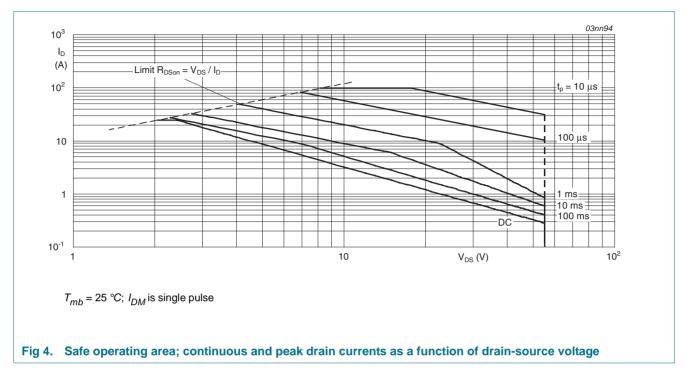
# BUK9Y40-55B

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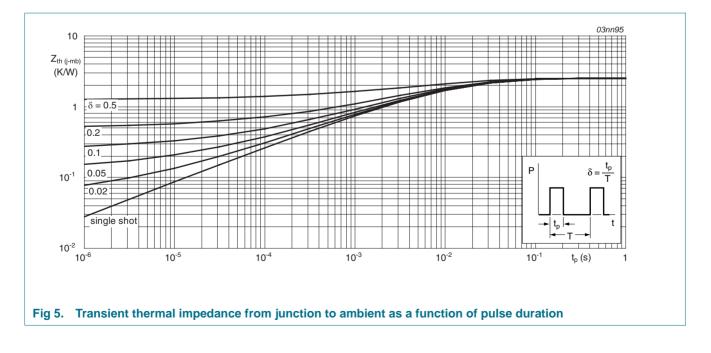
#### N-channel TrenchMOS logic level FET



### 5. Thermal characteristics

#### Table 5.Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	see <mark>Figure 5</mark>	-	-	2.5	K/W

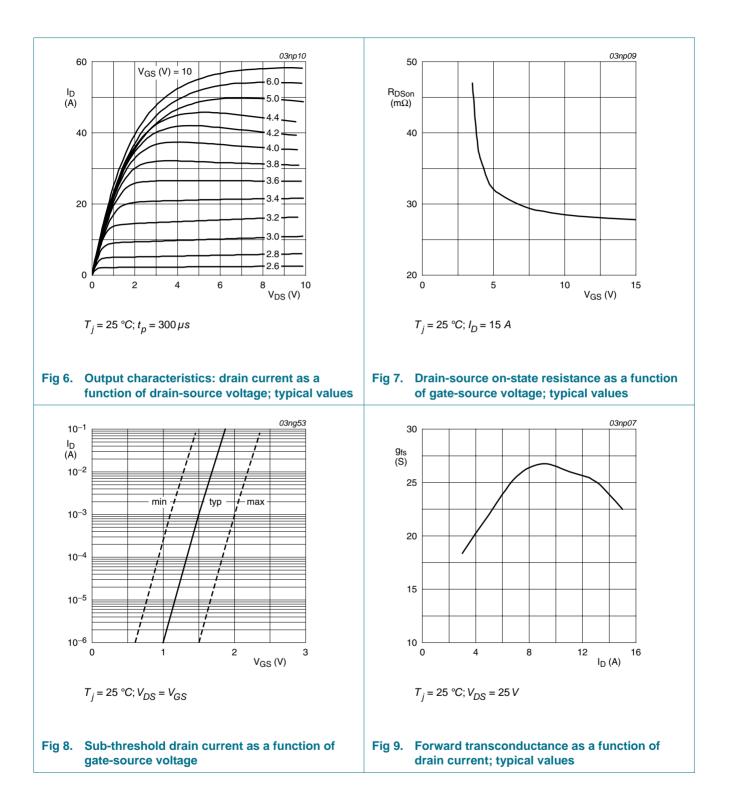


BUK9Y40-55B\_3

# 6. Characteristics

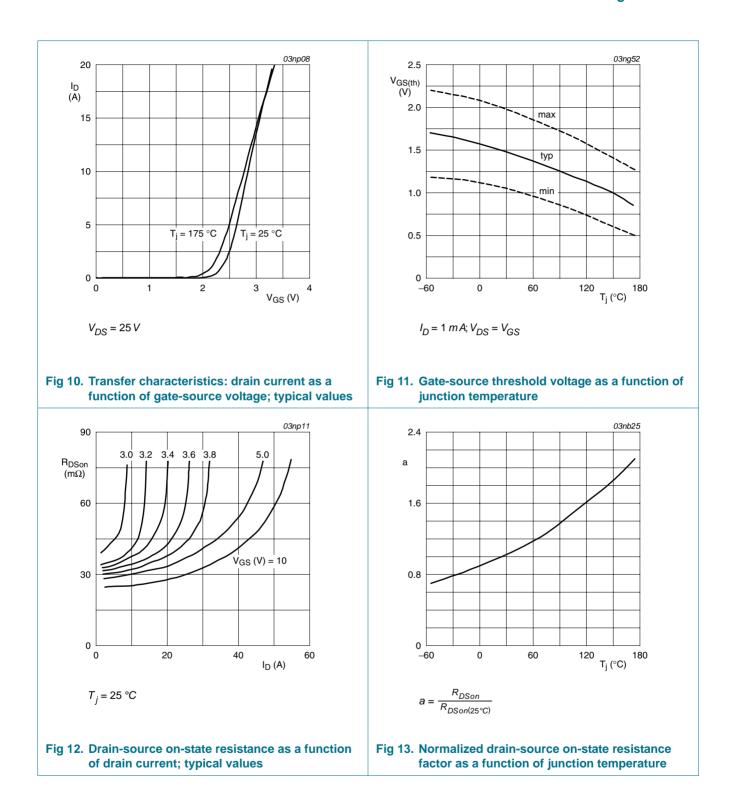
Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics					
(DR)000	drain-source breakdown voltage	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V};$ $T_j = 25 \text{ °C}$	55	-	-	V
		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V};$ $T_j = -55 \text{ °C}$	50	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS};$ $T_j = 175 \text{ °C}; \text{ see } \frac{\text{Figure } 11}{1}$	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C};$ see <u>Figure 11</u>	1.1	1.5	2	V
		$\begin{split} I_D &= 1 \text{ mA; } V_{DS} = V_{GS}; \\ T_j &= -55 ^\circ\text{C}\text{; see } \frac{\text{Figure } 11}{\text{Figure } 11} \end{split}$	-	-	2.3	V
I <sub>DSS</sub>	drain leakage current	$V_{DS}$ = 55 V; $V_{GS}$ = 0 V; $T_j$ = 25 $^\circ C$	-	0.02	1	μΑ
		V <sub>DS</sub> = 55 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C	-	-	500	μA
I <sub>GSS</sub>	gate leakage current	$V_{DS}$ = 0 V; $V_{GS}$ = 15 V; $T_j$ = 25 °C	-	2	100	nA
		$V_{DS} = 0 V; V_{GS} = -15 V;$ $T_j = 25 °C$	-	2	100	nA
Deen	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 15 \text{ A}; T_j = 175 \text{ °C};$ see <u>Figure 12</u> and <u>13</u>	-	-	84	mΩ
		$V_{GS}$ = 10 V; $I_{D}$ = 15 A; $T_{j}$ = 25 $^{\circ}C$	-	32	36	mΩ
		$V_{GS}$ = 4.5 V; $I_{D}$ = 15 A; $T_{j}$ = 25 $^{\circ}C$	-	-	45	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ °C};$ see <u>Figure 12</u> and <u>13</u>	-	34	40	mΩ
Source-d	rain diode					
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = 20 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; see <u>Figure 16</u>	-	0.85	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_{S} = 20 \text{ A}; \text{ d}I_{S}/\text{d}t = -100 \text{ A}/\mu\text{s};$	-	45	-	ns
Q <sub>r</sub> Dynamic	recovered charge	V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 30 V; T <sub>j</sub> = 25 °C	-	25	-	nC
Q <sub>G(tot)</sub>	total gate charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 44 V; V <sub>GS</sub> = 5 V;	-	11	-	nC
Q <sub>GS</sub>	gate-source charge	$T_j = 25 \text{ °C}; \text{ see } \frac{\text{Figure } 14}{\text{Figure } 14}$	-	2	-	nC
Q <sub>GD</sub>	gate-drain charge		-	5	-	nC
Ciss	input capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 25 V;	-	765	1020	pF
C <sub>oss</sub>	output capacitance	f = 1 MHz; T <sub>j</sub> = 25 °C;	-	123	148	pF
C <sub>rss</sub>	reverse transfer capacitance	- see <u>Figure 15</u>	-	71	97	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 30 \text{ V}; \text{ R}_{L} = 2.2 \Omega;$	-	17	-	ns
t <sub>r</sub>	rise time	$V_{GS} = 5 \text{ V}; \text{ R}_{G(ext)} = 10 \Omega;$	-	93	-	ns
t <sub>d(off)</sub>	turn-off delay time	– T <sub>j</sub> = 25 °C	-	35	-	ns
t <sub>f</sub>	fall time		_	72	-	ns

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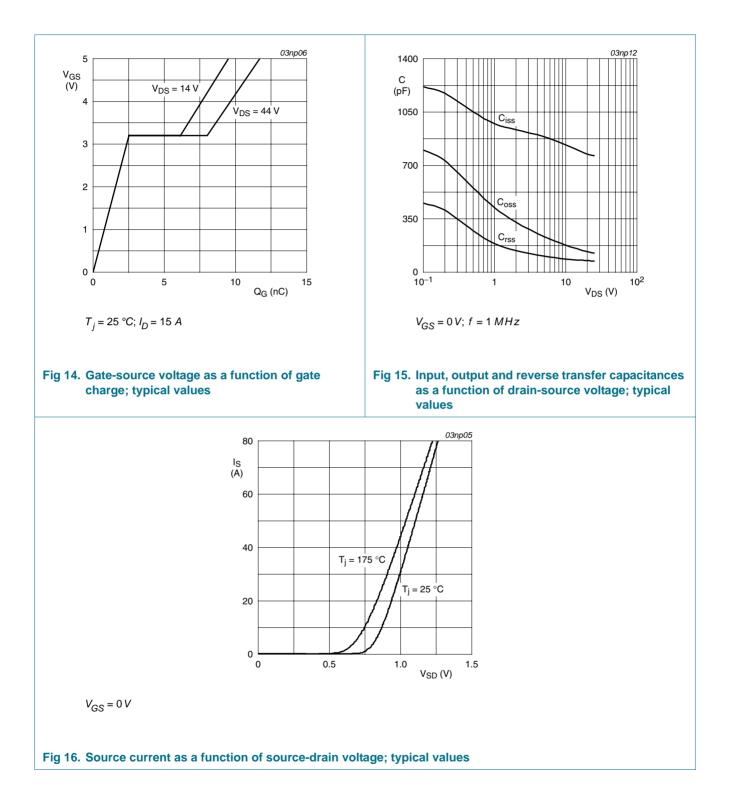


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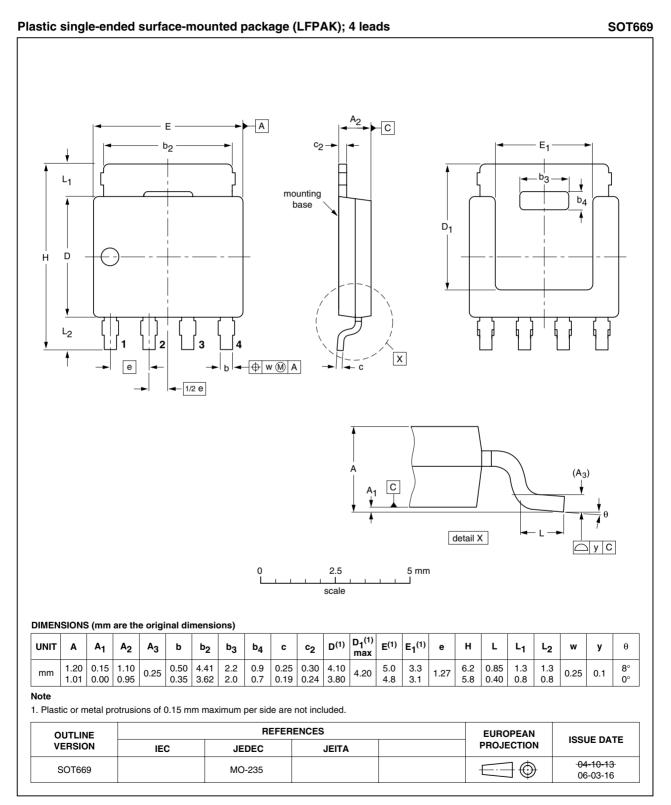
# BUK9Y40-55B N-channel TrenchMOS logic level FET



#### N-channel TrenchMOS logic level FET



### 7. Package outline



#### Fig 17. Package outline SOT669 (LFPAK)

# 8. Revision history

Table 7. Revision histo	ory			
Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK9Y40-55B_3	20080222	Product data sheet	-	BUK9Y40-55B_2
Modifications:		f this data sheet has been rede NXP Semiconductors.	esigned to comply w	th the new identity
	<ul> <li>Legal texts h</li> </ul>	ave been adapted to the new o	company name wher	e appropriate.
BUK9Y40-55B_2	20060411	Product data sheet	-	BUK9Y40_55B-01
BUK9Y40_55B-01	20040528	Product data sheet	-	-

# 9. Legal information

#### 9.1 Data sheet status

Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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